

## Fabrication of Nanogaps and Investigation of Molecular Junctions by Electrochemical Methods

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Schriften des Forschungszentrums Jülich  
Reihe Information / Information

Band / Volume 22

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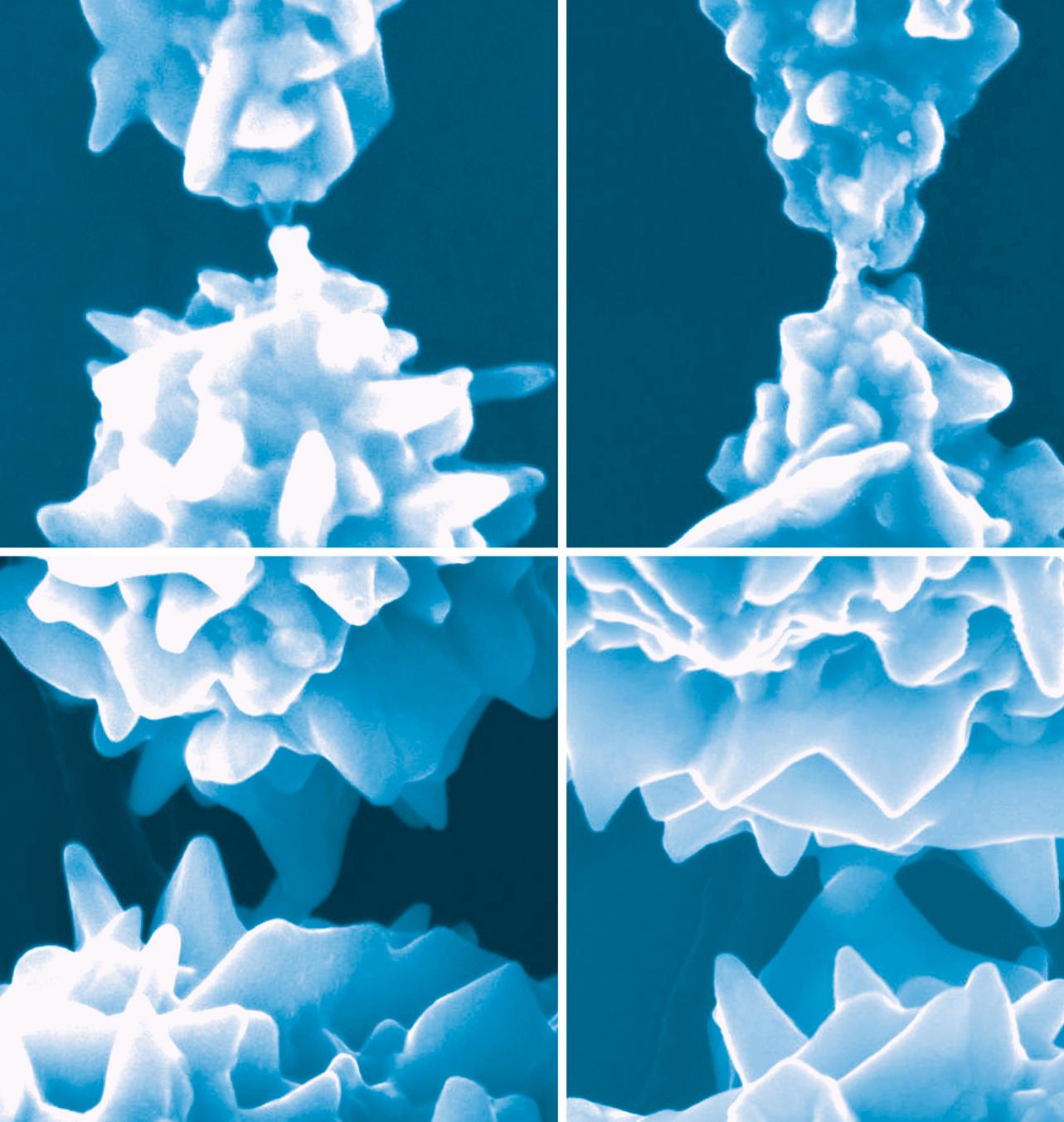
ISSN 1866-1777

ISBN 978-3-89336-812-9

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